



(54) **ELECTRONIC DEVICE AND MANUFACTURING METHOD THEREOF**

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(57) **ABSTRACT**

An electronic device and a method of manufacturing the electronic device are provided. The method of manufacturing the electronic device includes the following steps: providing a circuit board; performing a first pre-bending step on the circuit board so that the circuit board is bent to have a first radius of curvature; providing a back frame having a second radius of curvature; attaching the circuit board having the first radius of curvature to the back frame through an adhesive. A difference between the first radius of curvature and the second radius of curvature is within 10%.

